

PCN# 20140408002
Qualification of TI Malaysia as Additional
Assembly/Test Site for Select Devices
Change Notification / Sample Request

Date: 4/15/2014
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20140408002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPA3110D2PWP	null
TPA3110D2PWPR	null
TPA3111D1PWP	null
TPA3111D1PWPR	null
TPA3112D1PWP	null
TPA3112D1PWPR	null
TPA3113D2PWP	null
TPA3113D2PWPR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20140408002	PCN Date:	04/15/2014
Title:	Qualification of TI Malaysia as Additional Assembly/Test Site for Select Devices		
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037
Dept:	Quality Services		
Proposed 1st Ship Date:	07/15/2014	Estimated Sample Availability:	Date Provided at Sample request

Change Type:			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

Qualification of TI Malaysia as Additional Assembly/Test Site for Select Devices. Material differences are as follows:

- Group 1 – Devices that will have Mold Compound change only**

	MEX	MLA
Mold Compound	4205694, 4211880	4209640

- Group 2 – No material differences**

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Assembly Site		
TI Mexico	Assembly Site Origin (22L)	ASO: MEX
TI Taiwan	Assembly Site Origin (22L)	ASO: TAI
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2d:
 MSL '2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT: 39
 ITEM: LBL: 5A (L)T0:1750
 (1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CSO: SHE (21L) CCO:USA
 (22L) ASO: MLA (23L) ACO: MYS

ASSEMBLY SITE CODES: TI-Mexico = M, TI-Taiwan = T, [TI-Malaysia = K](#)

Product Affected: Group 1			
SN1106046D	TPS5402DR	TPS5403DR	TPS5405DR
SN1106046DR			
Product Affected: Group 2			
HPA00836PWPR	TPA3020D2PWPR	TPA3111D1PWPR	TPA3113D2PWP
HPA00928PWPR	TPA3110D2PWP	TPA3112D1PWP	TPA3113D2PWPR
HPA01070PWPR	TPA3110D2PWPR	TPA3112D1PWPR	
HPA01071PWPR	TPA3110LD2PWPR	TPA3112SD1PWP	
TPA3020D2PWP	TPA3111D1PWP	TPA3112SD1PWPR	

Group 1 : Qualification Data				
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle : TPS5405D (MSL1-260C)				
Package Construction Details				
Assembly Site:	MLA	Mold Compound:	4209640	
# Pins-Designator, Family:	8-D, SOIC	Mount Compound:	4042500	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
Electrical Characterization	-	30/0	-	-
Manufacturability Qualification (MQ)		Pass	-	-
**High Temp Storage Bake	170C (420 hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/150C (500 Cycles)	77/0	77/0	77/0
Moisture Sensitivity	L1-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 1-260C.				
Group 2 : Qualification Data				
Qual Vehicle 1 : SN89062PWP (MSL2-260C)				
Package Construction Details				
Assembly Site:	MLA	Mold Compound:	4205443	
# Pins-Designator, Family:	24-PWP, HTSSOP	Mount Compound:	4208458	
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	1.30 Mil Dia. Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size / Fail		
		Lot 1	Lot 2	Lot3
**Life test	125C (1000 hrs)	77/0	-	-
**Biased HAST	130C/85%RH (96 hrs)	77/0	77/0	77/0
**Autoclave	121C, 2atm (96 hrs)	77/0	77/0	77/0
**High Temp Storage Bake	150C (1000 hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/150C (500 Cycles)	77/0	77/0	77/0
**Thermal Shock	-65C/150C (500 Cycles)	77/0	77/0	77/0
Manufacturability Qualification (MQ)		Pass	-	-
Moisture Sensitivity	L2-260C	12/0	12/0	12/0
**- Preconditioning sequence: Level 2-260C.				

Qual Vehicle 2 : SN84001PWP (MSL2-260C)			
Package Construction Details			
Assembly Site:	MLA	Mold Compound:	4205443
# Pins-Designator, Family:	28-PWP, HTSSOP	Mount Compound:	4208458
Lead Finish, Base	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia. Cu
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions	Sample Size / Fail	
**Life test	125C (1000 hrs)	77/0	
**Biased Temp and Humidity	85C/85%RH (1000 hrs)	77/0	
**Autoclave	121C, 2atm (96 hrs)	77/0	
**High Temp Storage Bake	170C (420 hrs)	77/0	
**Temp Cycle	-65C/150C (500 Cycles)	77/0	
Manufacturability Qualification (MQ)		Pass	
**- Preconditioning sequence: Level 2-260C.			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com